

Material Declaration

BH13-1-XXXLF

Total mass of unit = 0.8395g

11/26/2009

BI Technologies Japan

Material Location	Material Name	Substance Name	CAS No.	Substance Mass.(mg)	Additional Information
Substrate	Aluminum ceramic	Aluminum oxide	1344-28-1	224.244	
		Silica	7631-86-9	8.914	
Thick film	Metals and oxides	Magnesium oxide	1300-78-3	7.021	
		Silver	7440-22-4	16.283	
		Lead monoxide(II)	7440-22-4	16.283	RoHS exemption/contained in glass section
		Silica	7631-86-9	5.149	
		Boron trioxide	1303-86-2	1.422	
		Zinc oxide	1313-13-2	0.842	
		Ruthenium oxide	1203-10-1	1.319	
		Trilead tetroxide	1314-41-6	1.038	RoHS exemption/contained in glass section
		Calcium oxide	1305-78-8	0.758	
		Chromium oxide(III)	1308-38-9	0.272	
		Aluminum oxide	1344-28-1	0.462	
		Ptadium	7440-20-3	0.125	
		Manganese carbonate(II)	598-67-9	0.151	
		Tantalum oxide(V)	1314-61-0	0.102	
		Copper	7440-50-8	0.084	
		Copper oxide(I)	1317-38-0	0.084	
		Copper oxide(II)	1317-39-1	0.084	
Bismuth oxide	1304-76-3	0.084			
Conformal coat and Marking	Epoxy/Acrylic	Rest		0.285	
		Bisphenol A/ epichlorhydrin based	25068-38-6	180.000	
		Silica	7631-86-9	109.800	
		Aluminum hydroxide	24645-51-2	79.200	
		BEA epichlorhydrin oligomer	40030-93-8	39.422	
		Trimellitic anhydride	552-60-7	12.500	
		Antimony trioxide	1309-64-4	4.572	
		Triphenyl phosphine	603-35-0	0.612	
		Carbon black	1333-86-4	0.185	
		Acrylic monomer oligomer	29570-58-9	0.185	
Termination	Phosphor bronze with Tin plating	Rest		5.178	
		Copper	7440-50-8	108.991	
		Tin	7440-31-5	11.703	
Junction and lead finish	Lead-free solder	Rest		0.206	
		Tin	7440-31-5	81.284	Lead finish: Hot dipped
		Silver	7440-22-4	2.533	
		Copper	7440-50-8	0.423	
		Rest		0.233	